L Number	Hits	Search Text	DB	Time stamp
1	887920	(substrate carrier board pcb ((printed wiring cirucit) adj4 board)) with (via through hole opening open)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 09:36
2	887920	(substrate carrier board pcb ((printed wiring circuit) adj4 board)) with (via through hole opening open)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 09:36
3	2576778	semiconductor chip die ic dice (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 09:37
4	345363	heat with (sink spreader radiate radiating radiated metal slug)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 09:45
5	6377	((substrate carrier board pcb ((printed wiring circuit) adj4 board)) with (via through hole opening open)) same (semiconductor chip die ic dice (integrated adj circuit)) same (heat with (sink spreader radiate radiating radiated metal slug))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 09:45
6	84318	bumps ball same (((substrate carrier board pcb ((printed wiring circuit) adj4 board)) with (via through hole opening open)) same (semiconductor chip die ic dice (integrated adj circuit)) same (heat with (sink spreader radiate radiating radiated metal slug)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 09:46
7	942	(bumps ball) same (((substrate carrier board pcb ((printed wiring circuit) adj4 board)) with (via through hole opening open)) same (semiconductor chip die ic dice (integrated adj circuit)) same (heat with (sink spreader radiate radiating radiated metal slug)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/25 09:46

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